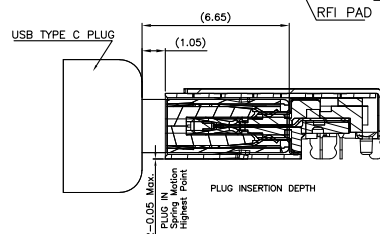
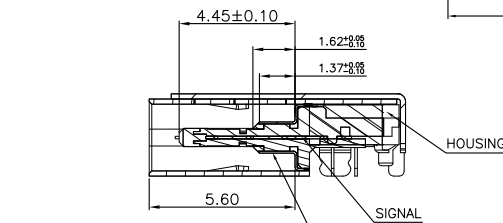
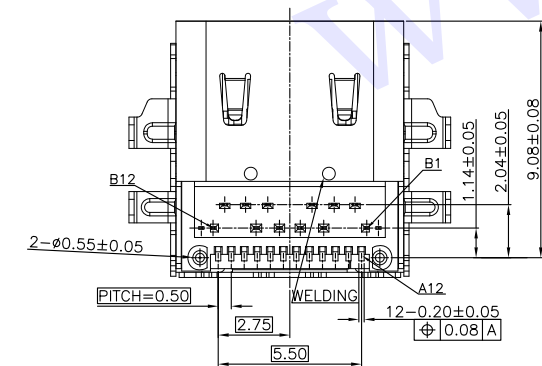
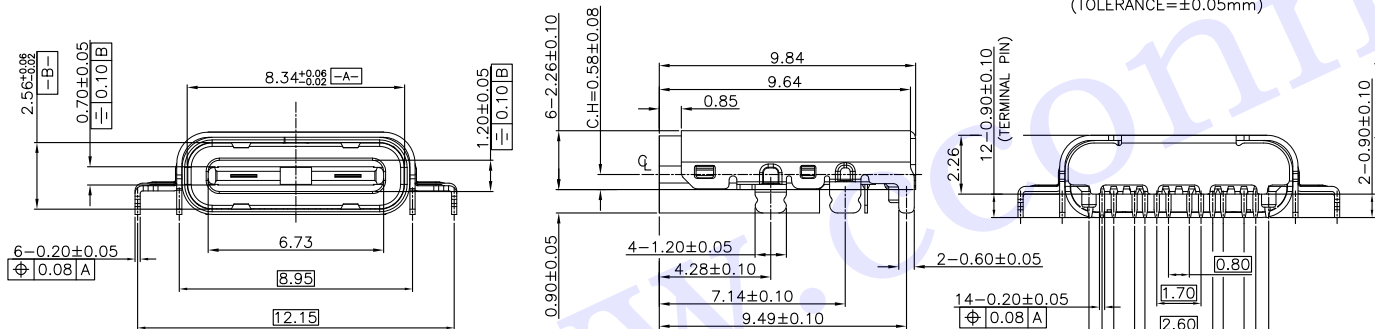


RECOMMENDED PCB LAYOUT(TOP VIEW)
(TOLERANCE=±0.05mm)



NOTES:

1.MATERIAL:

- 1.1 OUTSIDE SHELL: SUS301-1/2H T=0.20mm
- 1.2 INNER SHELL: SUS301-1/2H T=0.20mm
- 1.3 SIGNAL: SUS301-H T=0.10mm
- 1.4 RFI PAD: SUS301-H T=0.10mm
- 1.5 HOUSING: LCP+30%G.F. UL94 V-0 BLACK
- 1.6 TEMINARL: COPPER ALLOY T=0.10mm

2.PLATING SPECIFICATION

- 2.1 TERMINAL: SEE P/N
- 2.2 SHELL: NICKEL PLATED 60u"MIN.

3.MECHANICAL PERFORMANCE

- 3-1.INSERTION FORCE: 5N~20N.
- 3-2.WITHDRAWAL FORCE: INITIAL 8N~20N
AFTER 1000 MATING CYCLES 6N~20N.
- 3-3.DURABILITY: 10000 CYCLES.

4.ELECTRICAL PERFORMANCE

- 4-1.CURRENT RATING: 3A.
- 4-2.LLRCR: CONTACT: 40 mΩ MAX(INITIAL).
- 4-3.INSULATION RESISTANCE:UNMATED: 100 MΩ MIN.
- 4-4.DIELECTRIC WITHSTAND VOLTAGE: 100V AC.

5.IR REFLOW:

THE PEAK TEMPERATURE ON BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260±5°C.

6.OPERATING TEMPERATURE RANGE: -55°C~85°C.

7.RoHS COMPLIANT OR HALOGEN FREE COMPLIANT.

8.P/N PUC0310X0001

TERMINAL PLATING CODE:

- A: GOLD FLASH ON MATING AREA,
MATTE Sn 80~150u" ON SOLDERING AREA,
80~150u" NICKEL UNDER PLATING OVERALL
H: 2u"Au OVER 30u"Pd/Ni ON MATING AREA,
MATTE Sn 80~150u" ON SOLDERING AREA,
80~150u" NICKEL UNDER PLATING OVERALL

USB Type-C Receptacle Interface Pin Assignments							
Pin	Signal Name	Description	Mating Sequence	Pin	Signal Name	Description	Mating Sequence
A1	GND	Ground return	First	B12	GND	Ground return	First
A2	SSTxp1	Positive half of first SuperSpeed TX differential pair	Second	B11	SSRx1p	Positive half of first SuperSpeed RX differential pair	Second
A3	SSTxm1	Negative half of first SuperSpeed TX differential pair	Second	B10	SSRx1m	Negative half of first SuperSpeed RX differential pair	Second
A4	VBUS	Bus Power	First	B9	VBUS	Bus Power	First
A5	CC1	Configuration Channel	Second	B8	SBU2	Sideband Use (SBU)	Second
A6	Dp1	Positive half of the USB2.0 differential pair-Position 1	Second	B7	Dm2	Negative half of the USB2.0 differential pair-Position 2	Second
A7	Dn1	Negative half of the USB 2.0 differential pair-Position 1	Second	B6	Dp2	Positive half of the USB2.0 differential pair-Position 2	Second
A8	SBU1	Sideband Use (SBU)	Second	B5	CC2	Configuration Channel	Second
A9	VBUS	Bus Power	First	B4	VBUS	Bus Power	First
A10	SSRx2p	Negative half of second SuperSpeed RX differential pair	Second	B3	SSTx2p	Positive half of second SuperSpeed TX differential pair	Second
A11	SSRx2m	Positive half of second SuperSpeed RX differential pair	Second	B2	SSTx2m	Negative half of second SuperSpeed TX differential pair	Second
A12	GND	Ground return	First	B1	GND	Ground return	First

X.	±0.50	X.°	±2°	UNITS	mm
.X	±0.30	.X°	±1°		
.XX	±0.10	.XX°	±0.5°	MAT'L	/
.XXX	±0.05				
				FINISH	/
				Q'TY	

THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF CHUANGYUE TECHNOLOGY CO.,LTD. AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF CHUANGYUE TECHNOLOGY CO., LTD

深圳市创粤科技有限公司
TITLE:
TYPE C 24PIN 沉板0.8母座 板上2.26mm

APPD: /
CHKD: /
DR: Steven.Xie 2018/10/07

DWG NO.:
CY-LTF2-24PC-226
SCALE SHEET REV.
1/1 1/1 A1